

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2936472

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIH-HSUAN SUN	03/18/2014
WEI-YU YEH	03/18/2014
HSUEH-HUNG FU	05/04/2014
DONG JUNG SUEN	03/18/2014
RECEIVING PARTY DATA	
Name:	TSMC SOLID STATE LIGHTING LTD.
Street Address:	9, LI-HSIN 4TH ROAD
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14200069
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	2011-0833-C / 48047.180
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/
DATE SIGNED:	07/14/2014
Total Attachments: 3	
source=48047180_20110833C_Assignment#page1.tif	

PATENT

source=48047180_20110833C_Assignment#page2.tif

source=48047180_20110833C_Assignment#page3.tif

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|--|
| (1) | Chih-Hsuan Sun | of | No. 36-3, Lane 17, Linsen 2nd Road, Lingya District
Kaohsiung City, Taiwan, R.O.C. 802 |
| (2) | Wei-Yu Yeh | of | No. 8, Lane 300, Daxing Street, North District
Tainan City, Taiwan, R.O.C. 704 |
| (3) | Hsueh-Hung Fu | of | 4F, No. 22, Alley 6, Lane 485, Sec. 1, Kuan-Fu Road
Hsin-Chu, Taiwan, R.O.C. |
| (4) | Dong Jung Suen | of | 4F, No. 70, Qianxi Xin Cheng, Guangfeng Rd., Taoyuan
County
Guishan Township, Taiwan, R.O.C. 333 |

have invented certain improvements in

ENERGY STAR COMPLIANT LED LAMP

for which we have executed an application for Letters Patent of the United States of America, filed on March 7, 2014 and assigned application no. 14/200,069 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, TSMC Solid State Lighting Ltd., 9, Li-Hsin 4th Rd., HsinChu Science Park, HsinChu, Taiwan, ROC. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chih-Hsuan Sun

Residence Address: No. 36-3, Lane 17, Linsen 2nd Road, Lingya District
Kaohsiung City, Taiwan, R.O.C. 802

Dated: 2014.3.18

Chih-Hsuan Sun
Inventor Signature

Inventor Name: Wei-Yu Yeh

Residence Address: No. 8, Lane 300, Daxing Street, North District
Tainan City, Taiwan, R.O.C. 704

Dated: 2014.3.18

Wei Yu Yeh
Inventor Signature

Inventor Name: Hsueh-Hung Fu

Residence Address: 4F, No. 22, Alley 6, Lane 485, Sec. 1, Kuan-Fu Road
Hsin-Chu, Taiwan, R.O.C.

✓
Dated: 2014/4/4

✓ Hsueh-Hung Fu
Inventor Signature

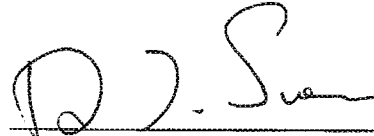
Assignment

Docket No.: 2011-0833-C /48047.180
Customer No.: 42717

Inventor Name: Dong Jung Suen

Residence Address: 4F, No. 70, Qianxi Xin Cheng, Guangfeng Rd., Taoyuan County
Guishan Township, Taiwan, R.O.C. 333

Dated: 3/8/2014


Inventor Signature